

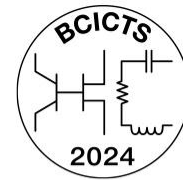
LNA in 130-nm InP HBT with 15.5 dB Gain and Record 5.3 dB Noise-Figure at 212 GHz

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U. Soyulu, M. Urtega, and M. Rodwell



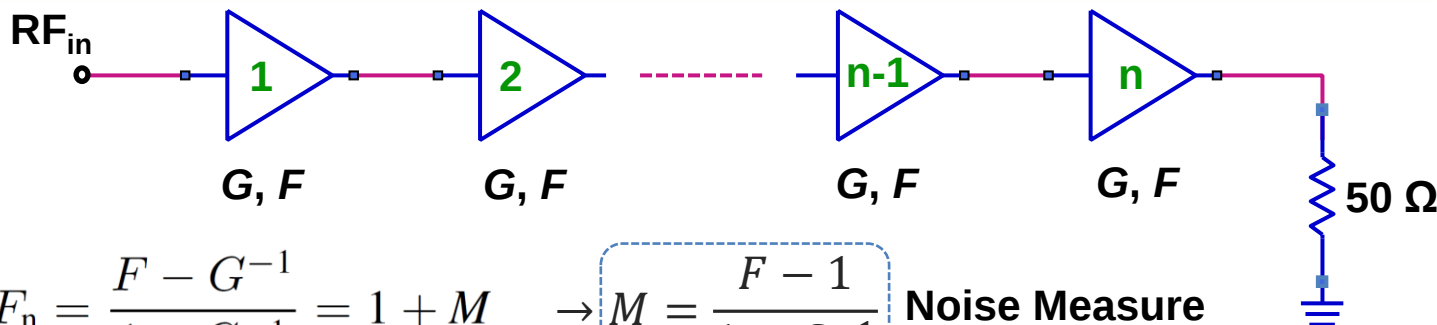
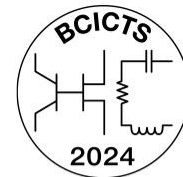
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Outline



- Noise Measure
- Motivation / Technology
- Noise-Measure in TSC130
- Circuit Design
- Results
- Comparison
- Conclusion

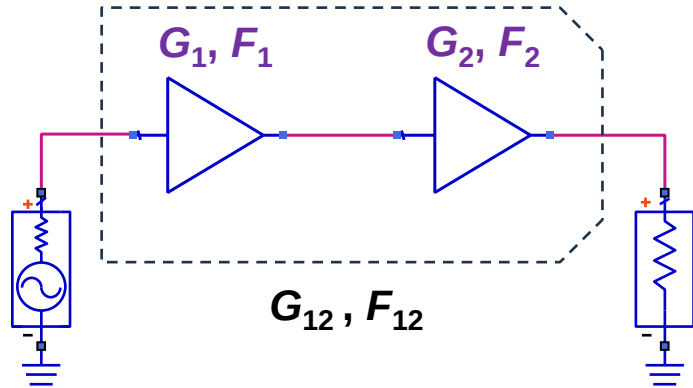
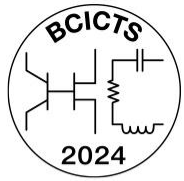
Noise Measure



$$\lim_{n \rightarrow \infty} F_n = \frac{F - G^{-1}}{1 - G^{-1}} = 1 + M \quad \rightarrow \quad M = \frac{F - 1}{1 - G^{-1}} \quad \text{Noise Measure}$$

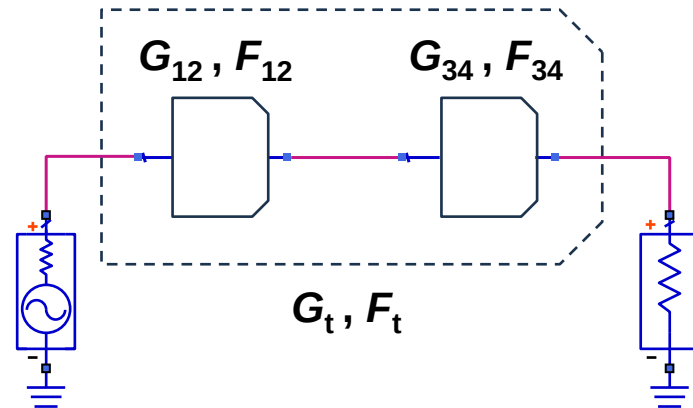
- M is independent of the circuit topology (e.g., common-emitter vs. common-base)
- M is independent of embedding or pre-embedding (passive, lossless) circuits that might be used for gain boosting or degeneration [11].
- A multi-stage LNA will have the same M as that of the transistors used in it.
- The goal is to find an LNA circuit whose passive element loss degrades M the least.

Noise Measure



$$M_{12} = \frac{F_{12} - 1}{1 - \frac{1}{G_1 G_2}} = M_1 + (M_2 - M_1) \frac{G_2 - 1}{G_1 G_2 - 1}$$

If $M_1 = M_2 \rightarrow M_{12} = M_1$



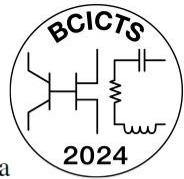
$$M_t = \frac{F_t - 1}{1 - \frac{1}{G_1 G_2 G_3 G_4}} = M_{12} + (M_{34} - M_{12}) \frac{G_3 G_4 - 1}{G_1 G_2 G_3 G_4 - 1}$$

$M_t = M_{12} = M_1$ if $M_{12} = M_{34}$

F_t is minimum if all stages have same noise measures.

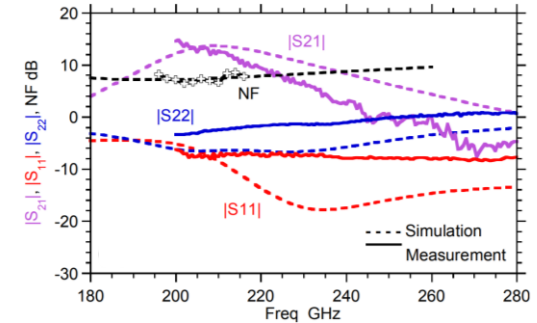
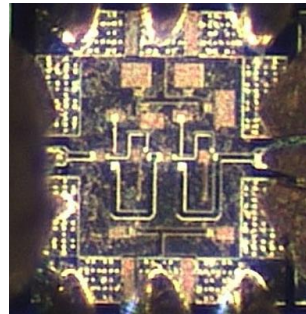
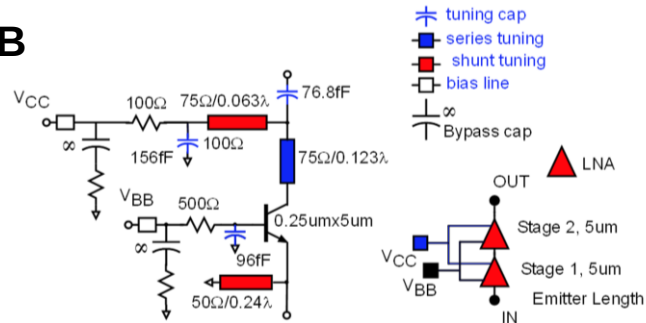
Only minimize the noise measure of the 1st stage.

Motivation / Previous Work

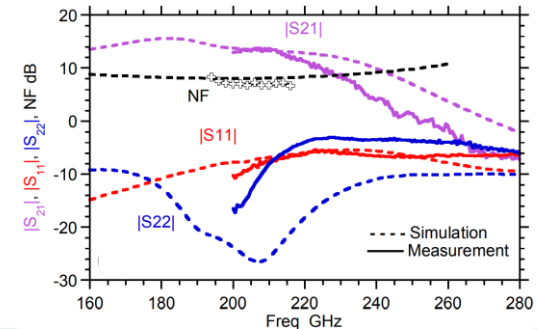
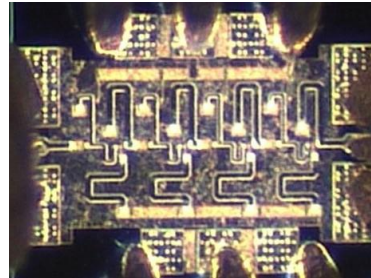
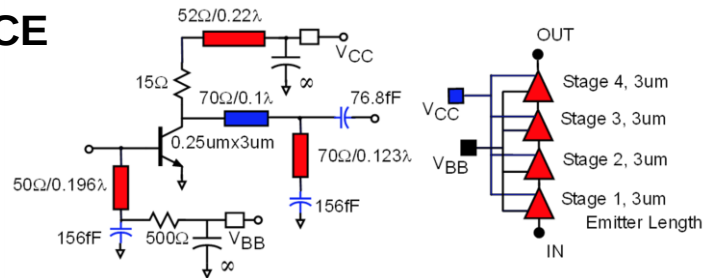


Reference [◇]	Technology	$f_T/f_{\max}$ (GHz/GHz)	Topology	3-dB Gain BW (GHz)	Gain [†] (dB)	NF (dB)	P_{DC} (mW)	Area (mm ²)
EuMC-2022 [9]	250-nm InP HBT	350/650	2-stage CB	196–216	14.5	6.7–8.1	9.2	0.21
EuMC-2022 [9]	250-nm InP HBT	350/650	4-stage CE	196–216	13	6.8–7.6	19.2	0.28

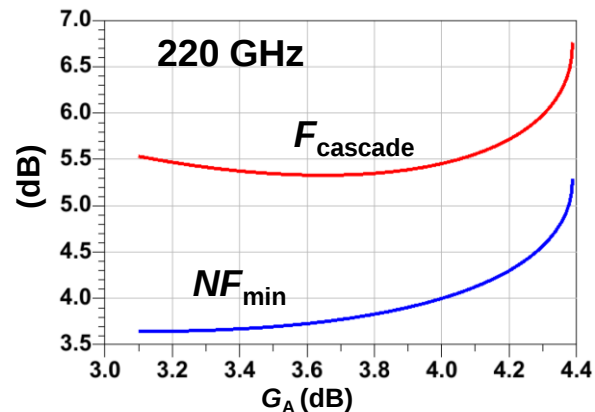
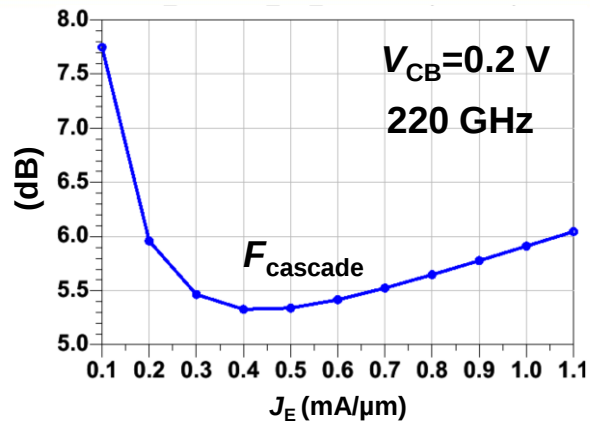
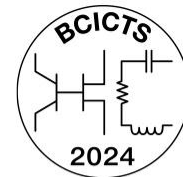
CB



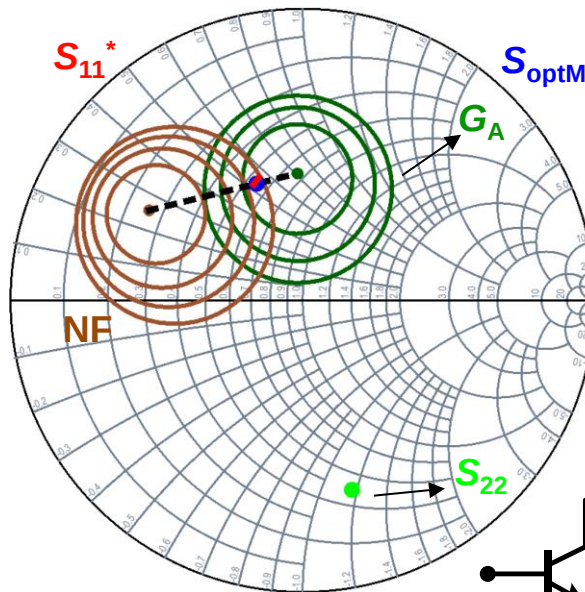
CE



Noise Measure in TSC130

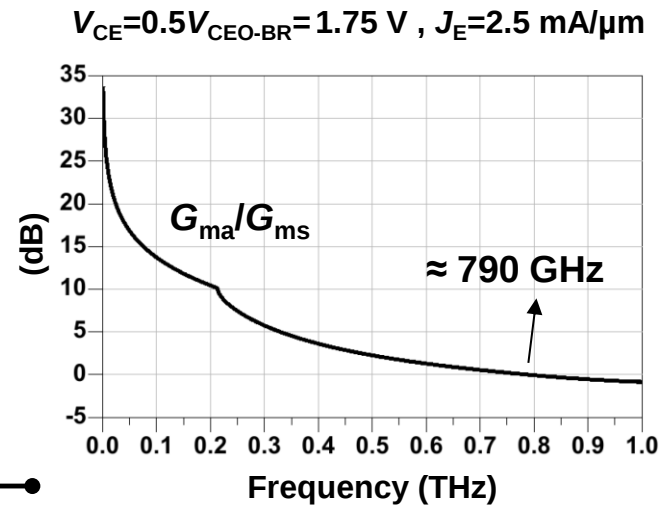
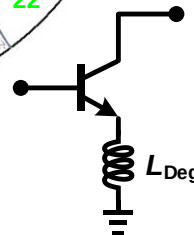


Common Emitter Transistor

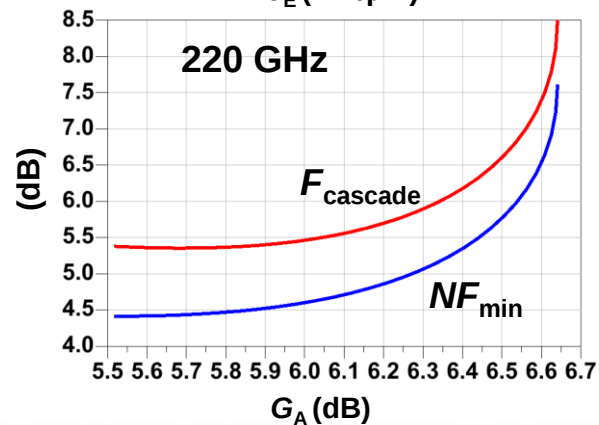
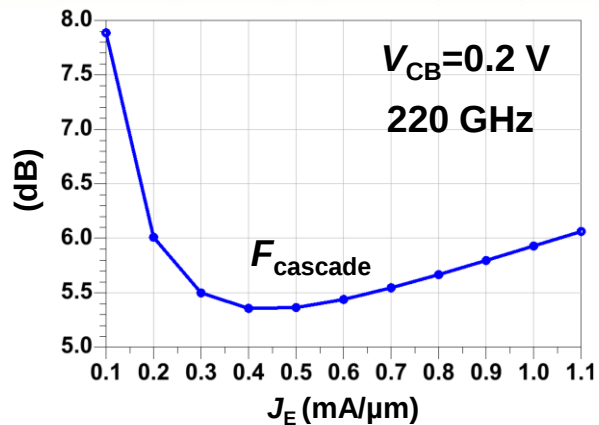
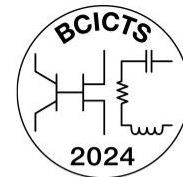


220 GHz

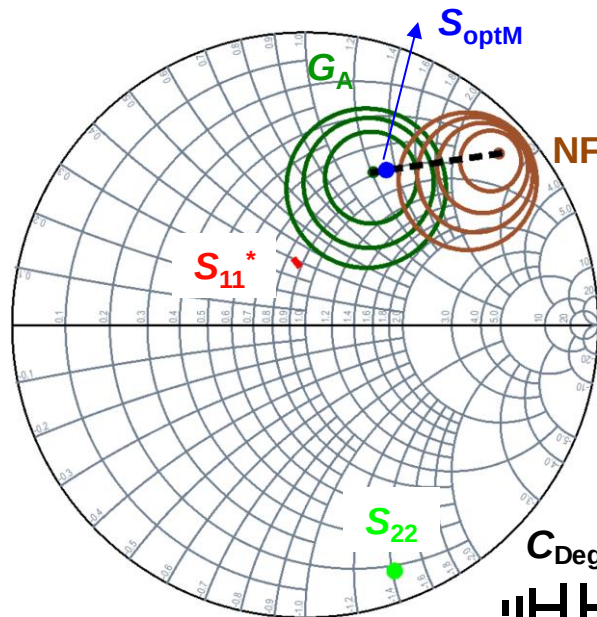
$L_{\text{deg}}=8\text{ fH}$



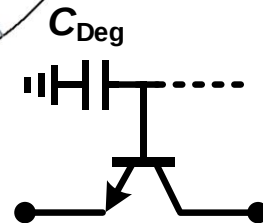
Noise Measure in TSC130



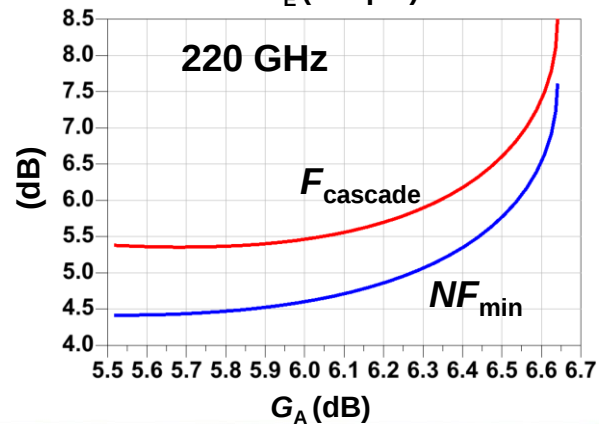
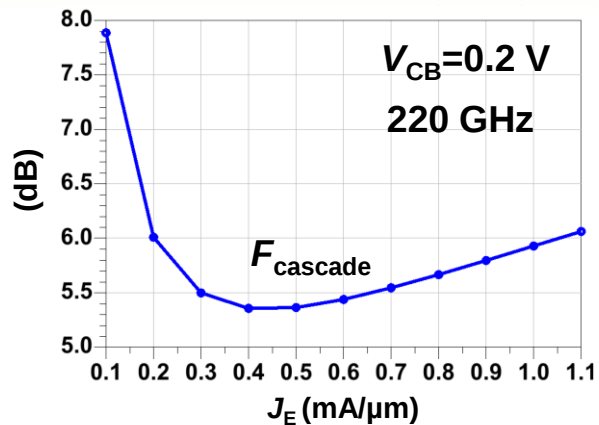
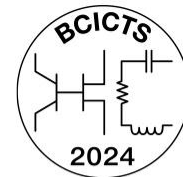
Common Base Transistor



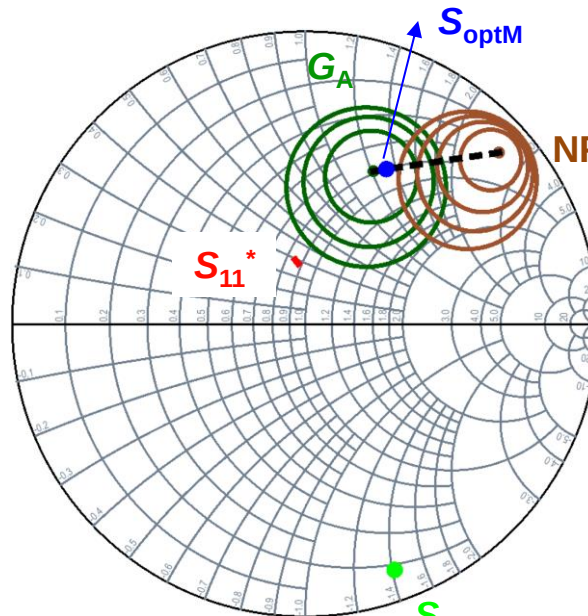
220 GHz
 $C_{\text{deg}}=15\text{ fF}$



Noise Measure in TSC130

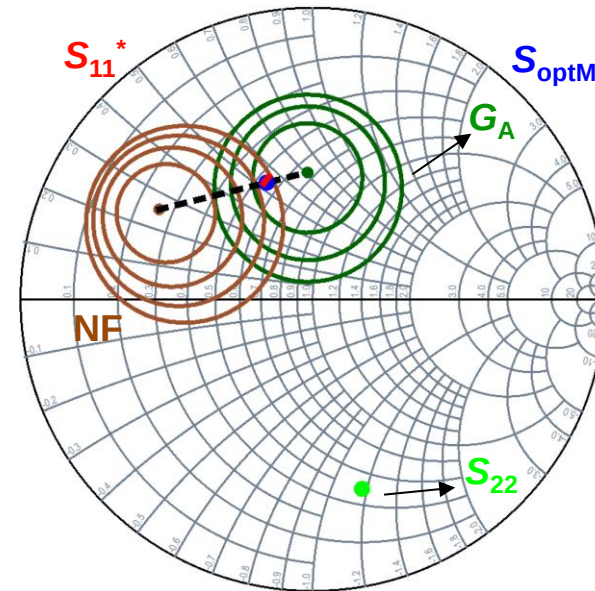


Common Base Transistor



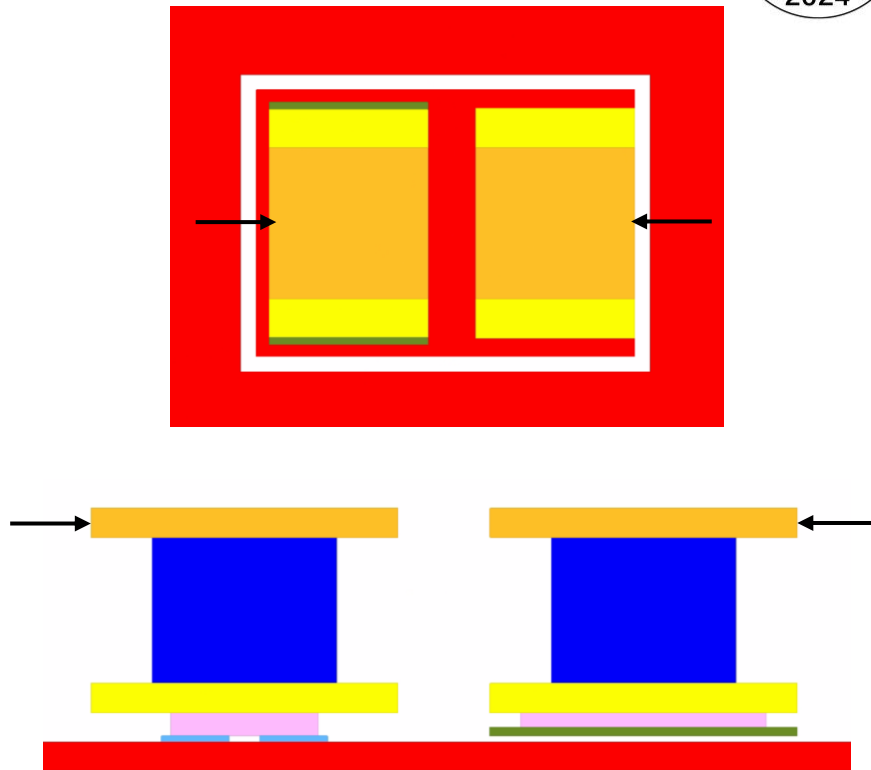
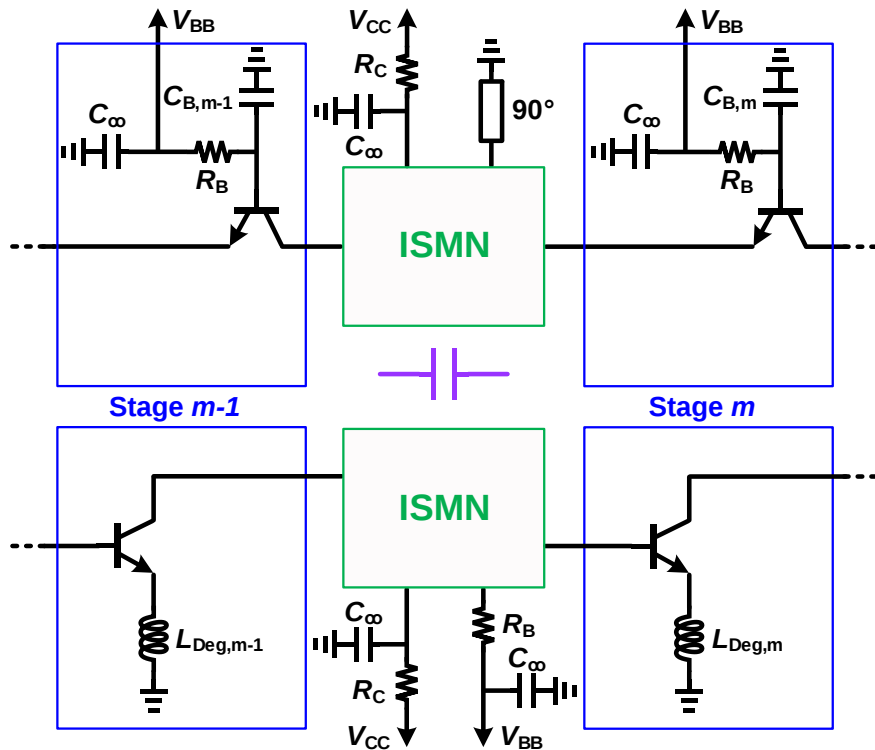
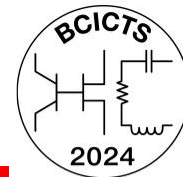
220 GHz
 $C_{\text{deg}}=15\text{ fF}$

CE

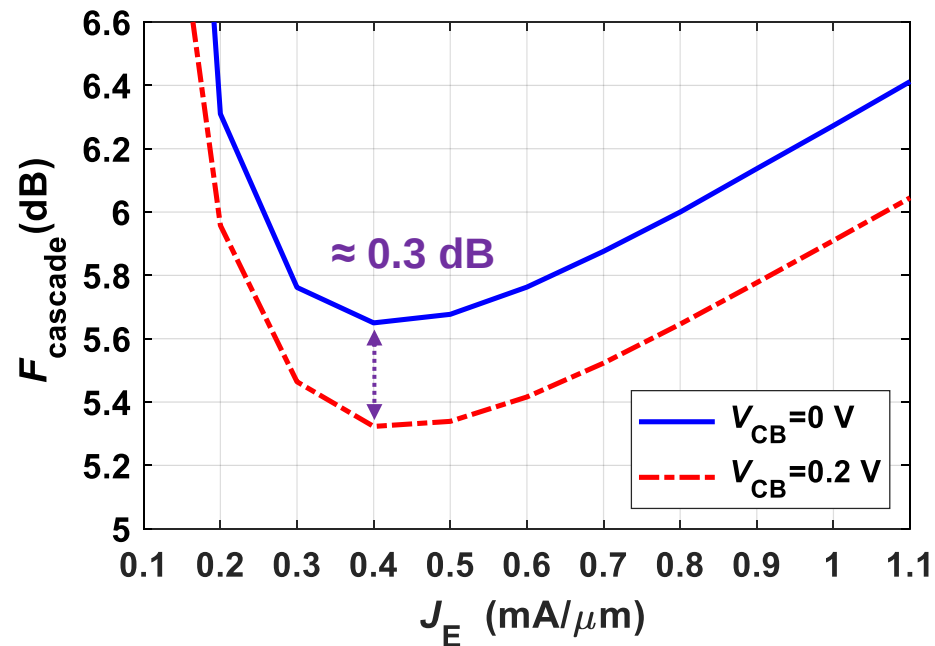
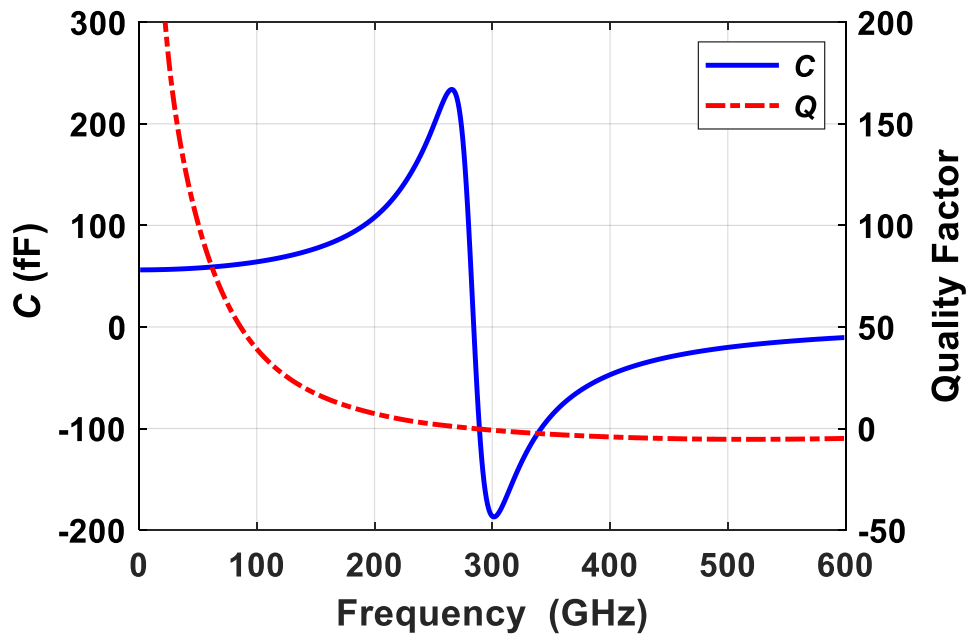
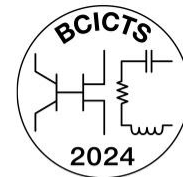


220 GHz
 $L_{\text{deg}}=8\text{ fH}$

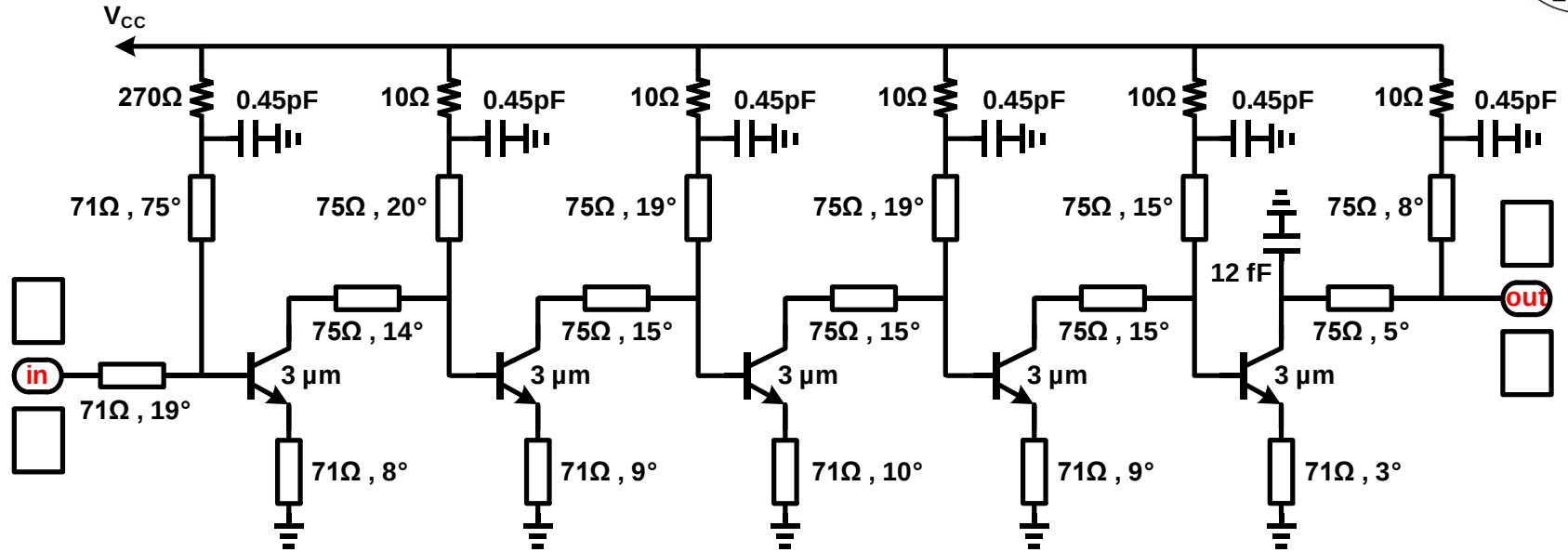
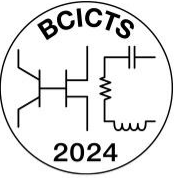
Design Considerations



Design Considerations

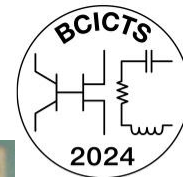


LNA Schematic



- Identical Stages.
- Slight tuning to compensate for coupling and EM parasitic.

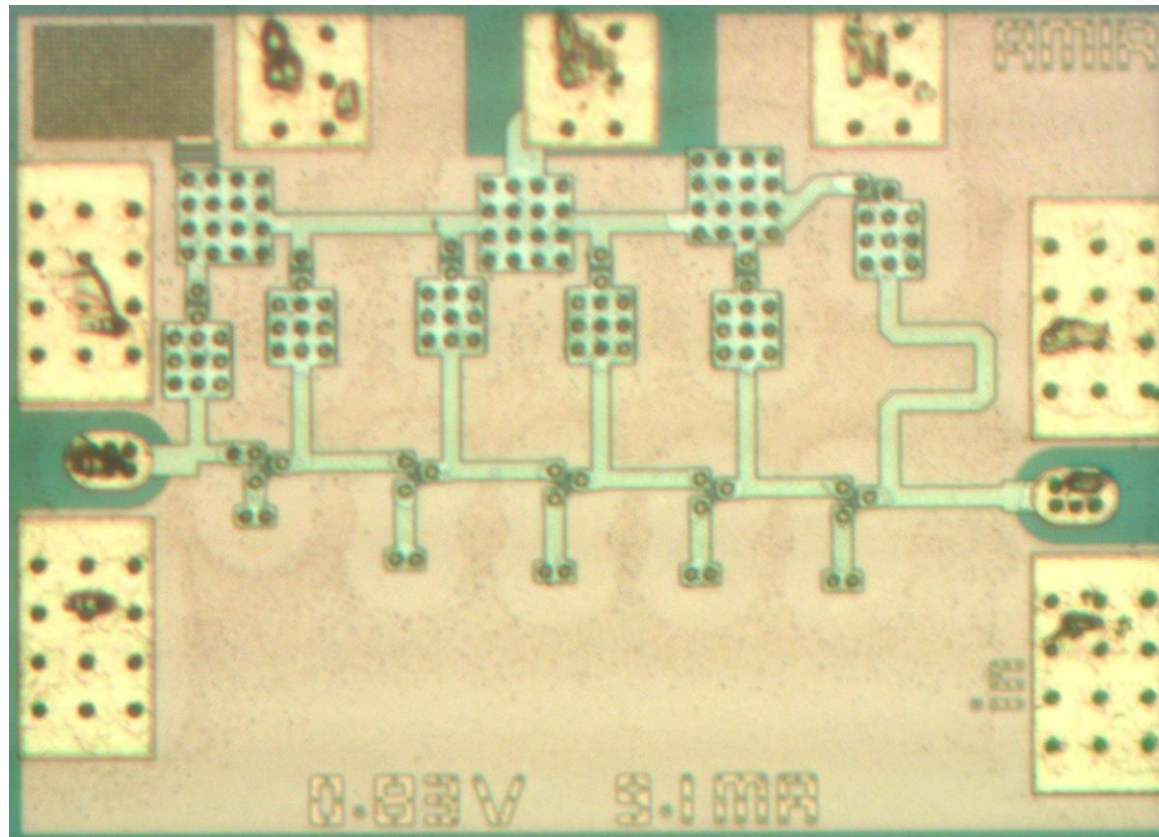
LNA Layout



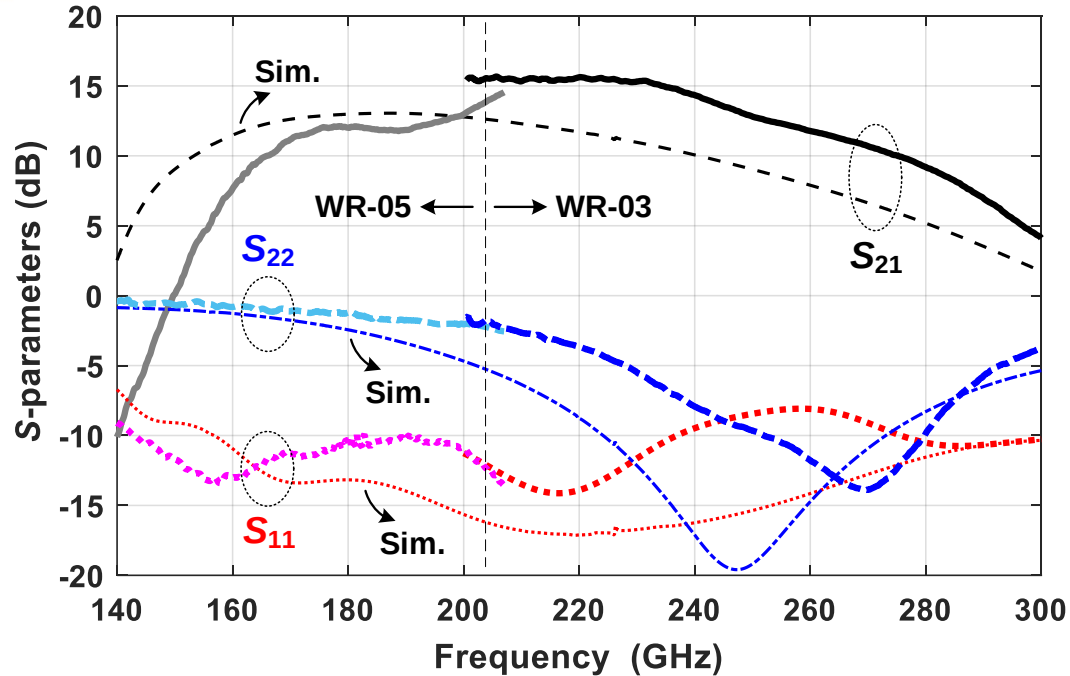
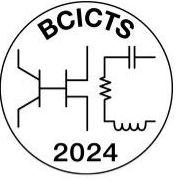
Technology:
Teledyne Scientific
130-nm InP DHBT

Chip Dimensions:
0.6 mm × 0.41 mm

Power Dissipation:
 $0.83 \times 9.1 = 7.55$ mW

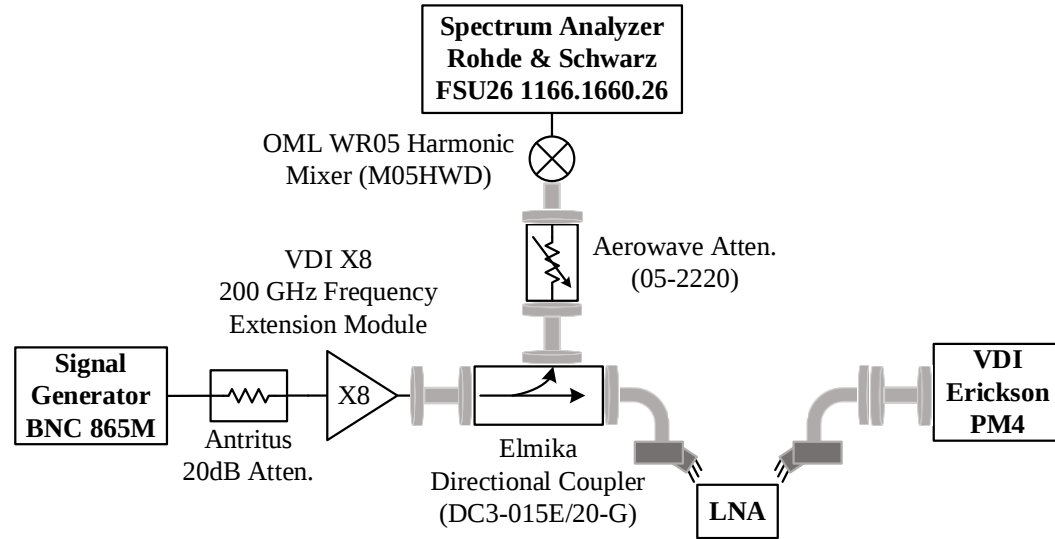
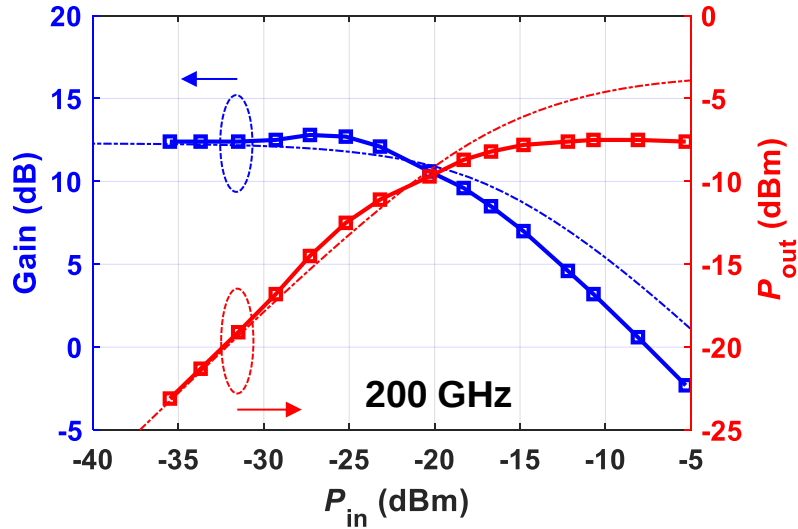
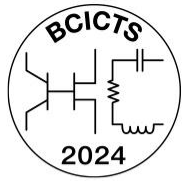


Results

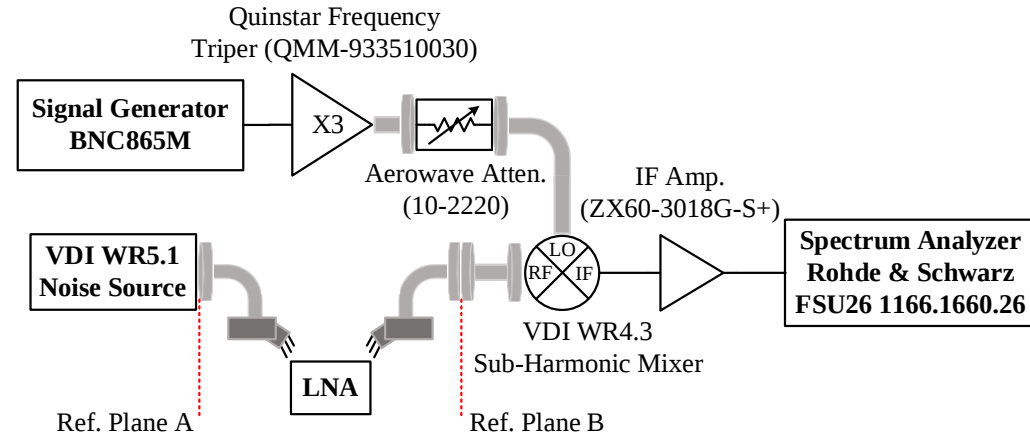
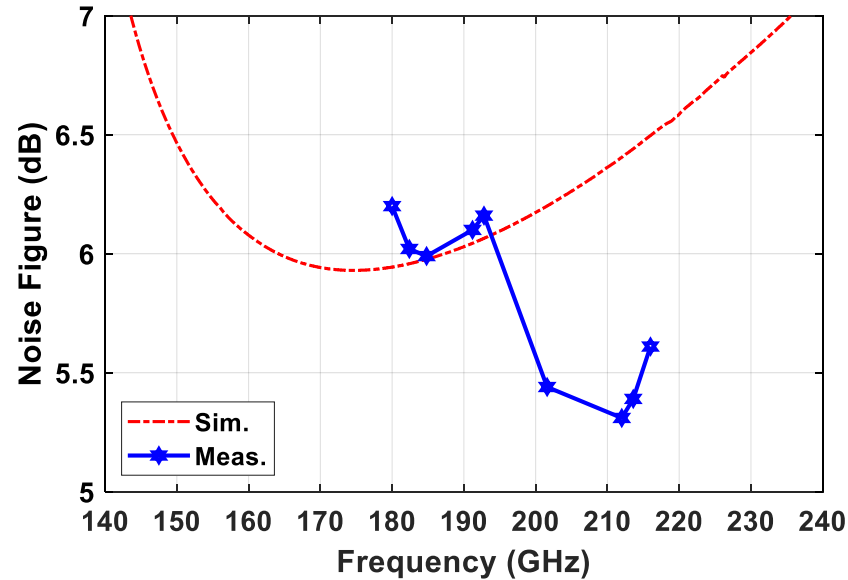
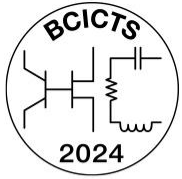


- Keysight PNA-X (N5245A) and OML extenders used.
- For WR-05 Measurements: power at probe tip (-15 dBm) $>$ LNA's input $P_{1\text{-dB}}$ (-23 dBm).

Results

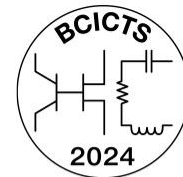


Results



- TSC's InP HBT processes have consistently shown a lower NF in measurements.
- This includes designs reported by UCSB [9], [15], Teledyne [7], [16], and others [17].

Comparison

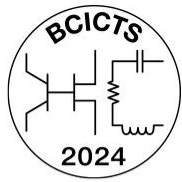


Performance Summary of Recently Published Low-Noise Amplifiers Operating Around 200-GHz.

Reference [◇]	Technology	$f_T/f_{\max}$ (GHz/GHz)	Topology	3-dB Gain BW (GHz)	Gain [†] (dB)	NF (dB)	P_{DC} (mW)	Area (mm ²)
EuMC-2022 [9]	250-nm InP HBT	350/650	2-stage CB	196–216	14.5	6.7–8.1	9.2	0.21
EuMC-2022 [9]	250-nm InP HBT	350/650	4-stage CE	196–216	13	6.8–7.6	19.2	0.28
EuMC-2021 [18]	130-nm SiGe BiCMOS	300/500	7-stage Cascode	236.8–250.8	28.5	13.7–14.2 [‡]	97.2	0.45
IMS-2023 [8]	130-nm SiGe BiCMOS	300/500	3-stage Cascode	183–208	18.1	9–10	35	0.55
IMS-2019 [4]	25-nm InP HEMT	NA	NA	215–225	20	3.9–4.5	NA	NA
MWTL-2024 [19]	35-nm InP HEMT	NA/866	4-stage CE	175–200	19.6	9.8–11.4	22	0.77
JSSC-2021 [20]	35-nm InGaAs mHEMT	> 500/1000	Distributed Amplifier	1–335	11	4.9* @ 160–205 GHz	90	0.53
This Work	130-nm InP HBT	500/1000	5-stage CE	>200–250	15.6	5.3–6.2 @ 180–216 GHz	7.6	0.25

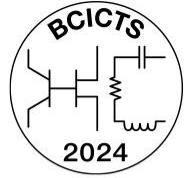
[◇]Spec values for other works were extracted/estimated from their text or plots. [†]Peak S_{21} . [‡]Simulation result. *BW: Bandwidth. *Average NF.

CONCLUSION



- Common-emitter is the optimal choice for mm-wave LNA design.
 - ✓ Better noise-measure and S_{11} match, better S_{22} , wideband, lower matching losses
- DC coupled design results in a lower NF by eliminating series capacitors.
- At 220-GHz, a 3- μm device in TSC130 features a simulated noise-measure of 5.3 dB, which is ≈ 1.5 lower than its counterparts in TSC250.
- An LNA with NF of 5.3~6.2 dB over 180-216 GHz, and $\approx 12\sim 15$ dB gain over 180-250 GHz were presented.
 - ✓ Lowest NF reported above 200-GHz for bipolar LNAs

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Thank You!

Questions?